

October 2013

FQB34N20

N-Channel QFET® MOSFET

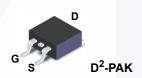
200 V, 31 A, 75 $m\Omega$

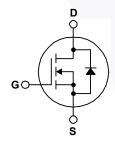
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 31 A, 200 V, $R_{DS(on)}$ = 75 m Ω (Max.) @ V_{GS} = 10 V, I_D = 15.5 A
- Low Gate Charge (Typ. 60 nC)
- Low Crss (Typ. 55 pF)
- 100% Avalanche Tested
- RoHS Complianty





Absolute Maximum Ratings $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		FQB34N20TM_AM002	Unit
V _{DSS}	Drain-Source Voltage		200	V
I _D	Drain Current - Continuous (T _C = 25°C)	31	Α
	- Continuous (T _C = 100°	C)	20	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	124	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	640	mJ
I _{AR}	Avalanche Current	(Note 1)	31	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	18	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		180	W
	- Derate above 25°C		1.43	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FQB34N20TM_AM002	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.7	
В	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (* 1 in² pad of 2 oz copper), Max.	40	

Package Marking and Ordering Information

Device Marking	Device	e Package Reel Size		Tape Width	Quantity
FQB34N20	FQB34N20 FQB34N20TM_AM002		330mm	24mm	800

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.2		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V		1	1	μΑ
	Zero Gate voltage Drain Current	V _{DS} = 160 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 15.5 A		0.06	0.075	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 15.5 \text{ A}$		25		S

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		2400	3100	pF
Coss	Output Capacitance	f = 1.0 MHz		430	560	pF
C _{rss}	Reverse Transfer Capacitance		-	55	70	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 34 A,			40	90	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$			280	570	ns
t _{d(off)}	Turn-Off Delay Time				125	260	ns
t _f	Turn-Off Fall Time	(Note	4)	/	115	240	ns
Q_g	Total Gate Charge	V _{DS} = 160 V, I _D = 34 A,			60	78	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			17		nC
Q _{gd}	Gate-Drain Charge	(Note	4)		27		nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		 -	31	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		 -	124	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 31 A	 	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 34 A,	 150		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	 0.95		μC

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 1.0mH, I_{AS} = 31A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. I_{SD} ≤ 34A, di/dt ≤ 300A/ μ s, V_{DD} ≤ BV $_{DSS}$, Starting T_{J} = 25°C 4. Essentially independent of operating temperature

Typical Characteristics

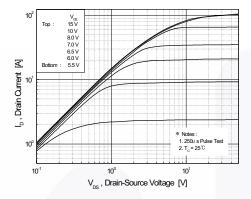


Figure 1. On-Region Characteristics

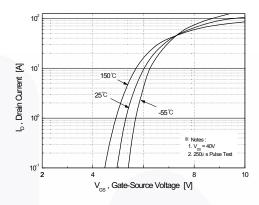


Figure 2. Transfer Characteristics

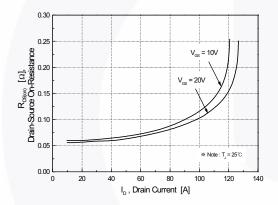


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

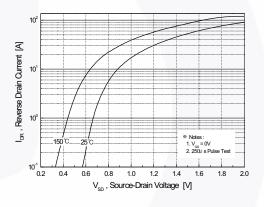


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

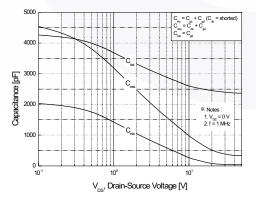


Figure 5. Capacitance Characteristics

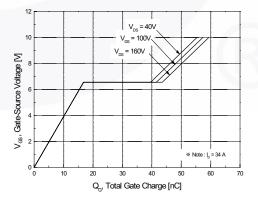


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

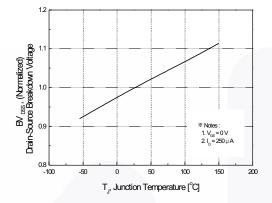


Figure 7. Breakdown Voltage Variation vs. Temperature

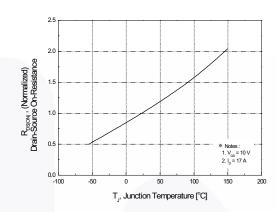


Figure 8. On-Resistance Variation vs. Temperature

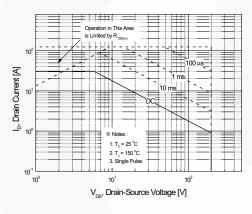


Figure 9. Maximum Safe Operating Area

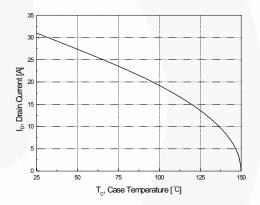


Figure 10. Maximum Drain Current vs. Case Temperature

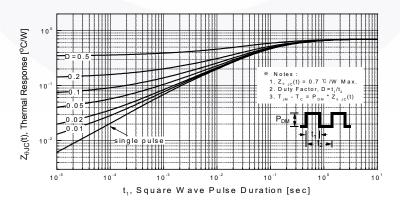


Figure 11. Transient Thermal Response Curve



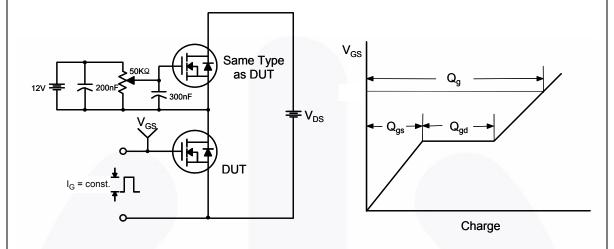


Figure 13. Resistive Switching Test Circuit & Waveforms

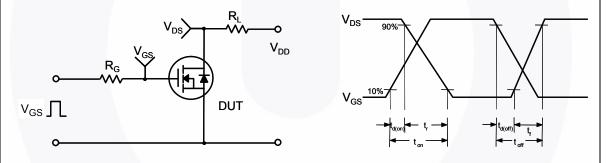
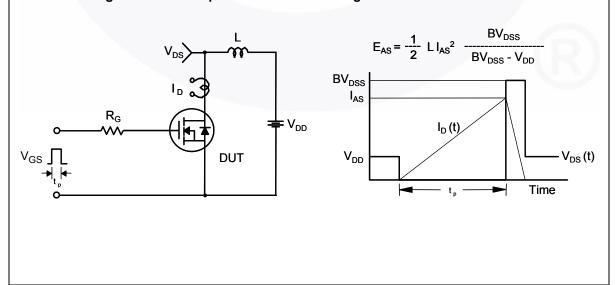
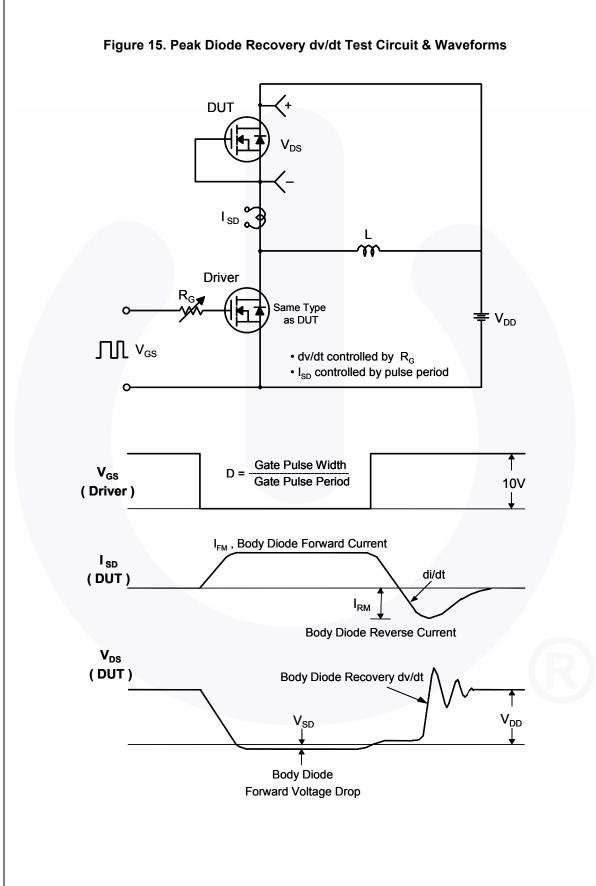


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





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FQB34N20 Rev. C1

Mechanical Dimensions

TO-263 2L (D²PAK)

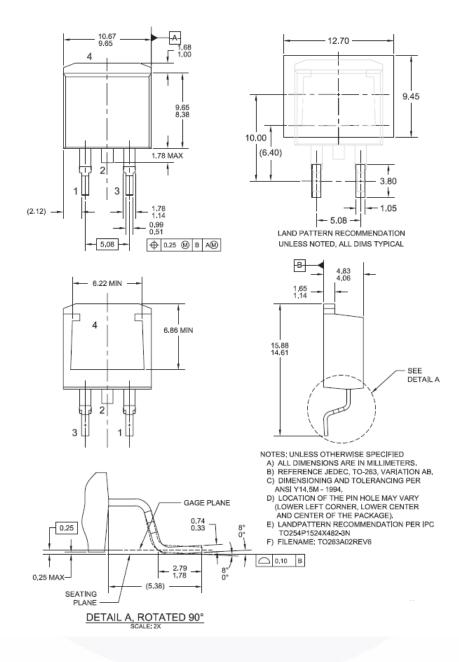


Figure 16. 2LD, TO263, Surface Mount

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Dimension in Millimeters





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